

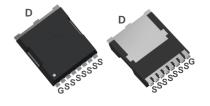
# DTT066N04SJ

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# N-Channel 40 V (D-S) Super Junction MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (mΩ) (Typ.)	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
40	0.55 at V <sub>GS</sub> = 10 V	425	82 nC			

## **TOLL Pin Configuration**

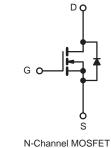


## FEATURES

- DT-SJ Power MOSFET
- Very low on-resistance
- Excellent gate charge x R<sub>DS(on)</sub> product(FOM)

#### **APPLICATIONS**

- Power Management
- Motor Drivers
- DC-DC Converters



<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_C = 25 \text{ °C}$ , unless otherwise noted)						
PARAMETER	SYMBOL	LIMIT	UNIT			
Drain-Source Voltage	V <sub>DS</sub>	40	V			
Gate-Source Voltage	V <sub>GS</sub>	± 20	v			
Continuous Drain Current ( $T_{,1} = 175 \ ^{\circ}C$ ) <sup>a</sup>	$T_C = 25 \ ^{\circ}C$		425	A		
Continuous Drain Current $(T_j = T/5^{-1}C_j)^{-1}$	T <sub>C</sub> = 100 °C	I <sub>D</sub>	330			
Pulsed Drain Current <sup>b</sup>	I <sub>DM</sub>	1480				
Single Avalanche Energy	E <sub>AS</sub>	872	mJ			
Maximum Power Dissipation <sup>c</sup>	T <sub>C</sub> = 25 °C	P <sub>D</sub>	350 <sup>c</sup>	W		
	T <sub>C</sub> = 100 °C	ΓD	175	vv		
Operating Junction and Storage Temperature Ran	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	ŝ			
Soldering Recommendations (Peak Temperature)		260	°C			

THERMAL RESISTANCE RATINGS							
PARAMETER	SYMBOL	LIMIT	UNIT				
Junction-to-Ambient (PCB Mount) <sup>d</sup>	R <sub>thJA</sub>	32	°C/W				
Junction-to-Case (Drain)	R <sub>thJC</sub>	0.42	0/11				

Notes

a. Calculated continuous current based on maximum allowablejunction temperature.

- b. Repetitive rating; pulse width limited by max. junction temperature.
- c. Pd is based on max. junction temperature, using junction-case thermal resistance.
- d. The value of ReuA is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with Ta=25 °C.



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static				•			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	40 -	-	v		
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS},I_{D}=250\;\mu A$	2	-	4	v	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS}$ = 0 V, $V_{GS}$ = ± 20 V	-	-	± 100	nA	
Zero Gate Voltage Drain Current		$V_{DS} = 40 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	1		
Zero Gale voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 40 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	100	μA	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V},  V_{GS} = 10 \text{ V}$	425	-	-	А	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 30 \text{ A}$	-	0.55	0.66	mΩ	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 5 V, I_{D} = 30 A$	-	100	-	S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>		-	6155	-	pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V, V_{DS} = 20 V, f = 1 MHz$	-	3030	-		
Reverse Transfer Capacitance	C <sub>rss</sub>		-	108	-		
Total Gate Charge <sup>c</sup>	Qg		-	82	-	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$	-	28	-		
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>		-	15	-		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	-	1.5	-	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>		-	6	-		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DS}$ = 20 V, $I_{D}$ = 30 A, $R_{g}$ = 2.5 $\Omega$	-	15	-	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	V <sub>GS</sub> = 10 V	-	22	-		
Fall Time <sup>c</sup>	t <sub>f</sub>		-	10	-		
Drain-Source Body Diode Ratings and	Characterist	ti <b>cs</b> <sup>b</sup> (T <sub>C</sub> = 25 °C)					
Continuous Source-Drain Diode Current	۱ <sub>S</sub>	T <sub>C</sub> = 25 °C	-	-	425	А	
Pulsed Current (t = 100 µs)	I <sub>SM</sub>		-	-	1700	А	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	$I_{F} = 2 \text{ A}, V_{GS} = 0 \text{ V}$	-	-	1.2	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/μs	-	45	-	ns	
Reverse Recovery Charge	Q <sub>rr</sub>	$i_F = 20 A$ , $u_I/u_I = 100 A/\mu_S$	-	50	-	nC	

#### Notes

a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$ 

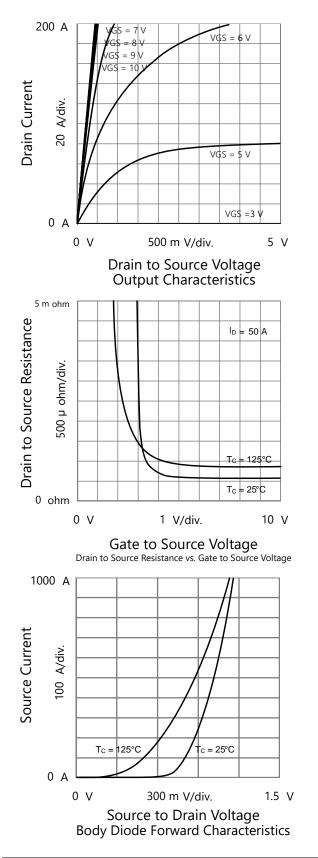
b. Guaranteed by design, not subject to production testing.

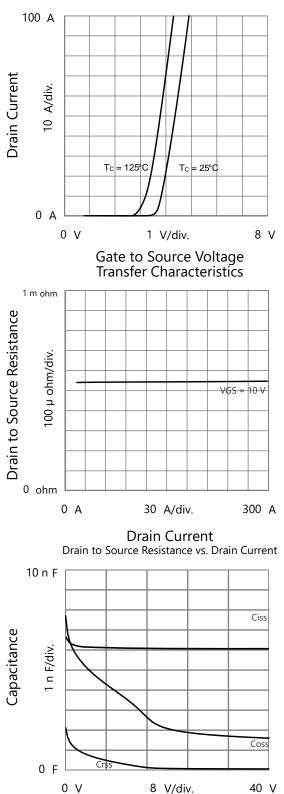
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



## TYPICAL CHARACTERISTICS (25 C, unless otherwise noted)

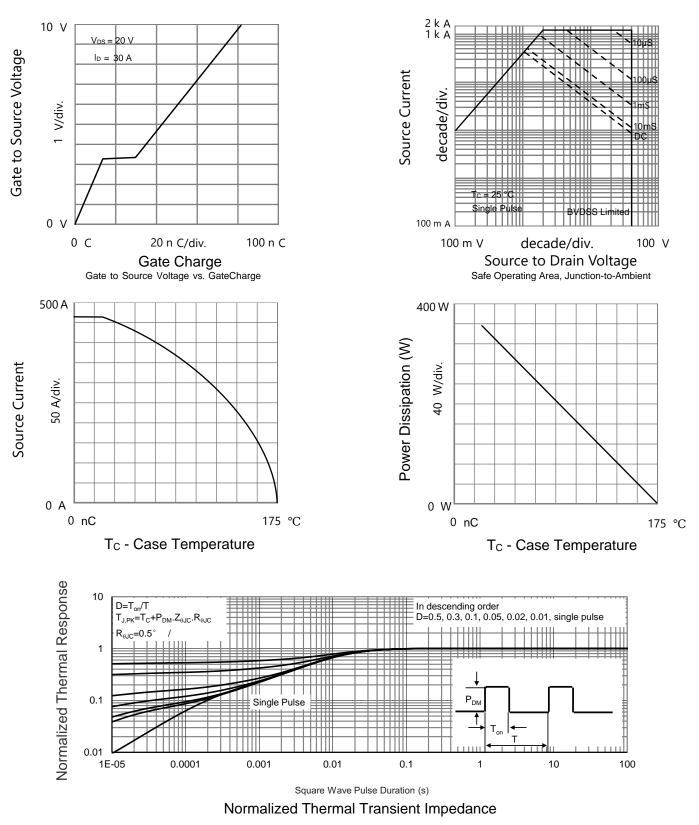




Drain to Source Voltage Capacitances

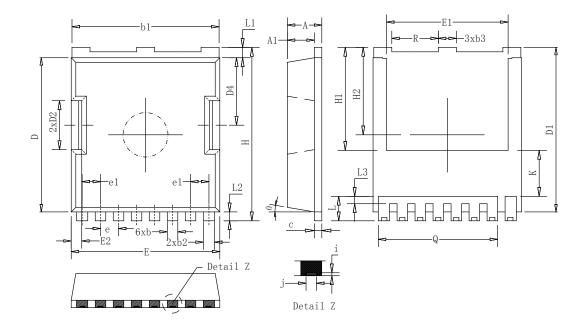


## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





# **TOLL PACKAGE OUTLINE**



### COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

Symbol	Min	Тур	Max	Symbol	Min	Тур	Max
A	2.05	2.30	2.65	E2	0.40	0.70	0.90
A1	1.50	1.80	2.10	Н	11.30	11.70	12.10
b	0.50	0.70	0.90	H1	6.95 BSC		
b1	9.50	9.80	10.05	H2	5.90 BSC		
b2	0.50	0.75	1.00	i	0.10 REF		
b3	1.00	1.20	1.45	j	0.35 REF		
c	0.30	0.50	0.75	K	3.10 REF		
D	10.10	10.40	10.70	L	1.45	1.65	1.85
D1	10.80	11.10	11.40	L1	0.50	0.70	0.90
D2	3.10	3.30	3.50	L2	0.40	0.60	0.80
D4	4.35	4.55	4.80	L3	0.30	0.50	0.70
e	1.20 BSC			Q	7.95 REF		
e1	1.225 BSC			R	2.80	3.10	3.35
Е	9.65	9.90	10.15	θ	10°REF		
E1	7.80	8.10	8.50				



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